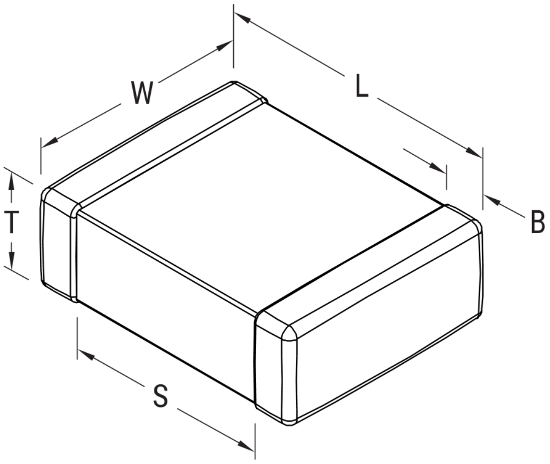
C1808X332JBGACTU

Aliases (C1808X332JBGAC7800)

SMD Comm C0G HV Flex, Ceramic, 3300 pF, 5%, 630 VDC, C0G, SMD, MLCC, FT-CAP, Ultra-Stable, 1808



Click here for the 3D model.

Dimensions

Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
T	1.4mm +/-0.15mm
S	2.9mm MIN
B	0.7mm +/-0.35mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

General Information

Series	SMD Comm C0G HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	false
AEC-Q200	No
Typical Component Weight	62 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	3300 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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